



**Ironwood**  
ELECTRONICS

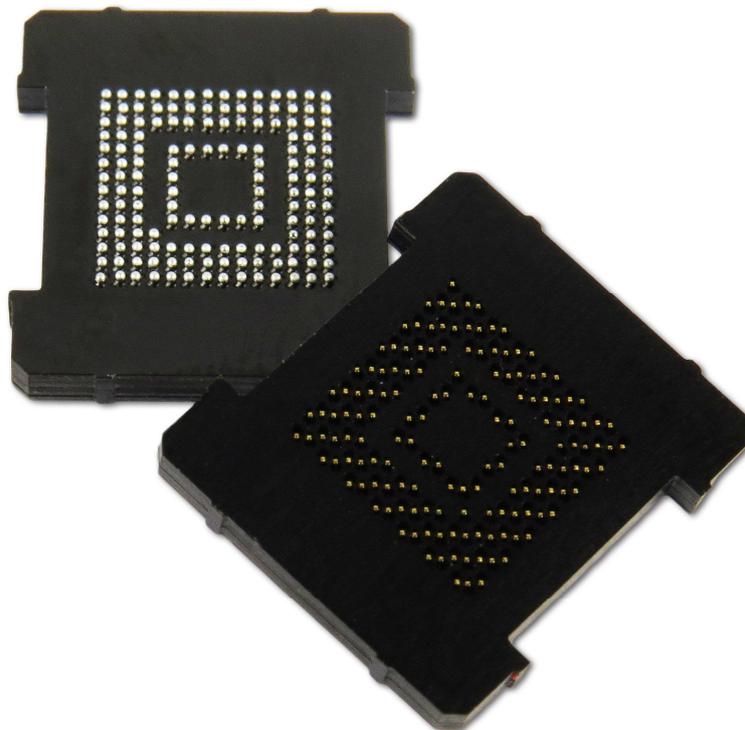


**High Performance**  
**Sockets & Adapters**

## Grypper sockets for UFS and eMMC devices are available from Ironwood

*Grypper Sockets Available for new form factor eMMC and UFS4.0*

EAGAN, MN - July, 2022 Ironwood Electronics, continues to design and manufacture new Grypper test sockets for eMMC and UFS BGA devices. The Grypper sockets support the variety of sizes that 153 ball eMMC and UFS devices are produced, ranging from 7.5 x 7.5 mm to the 11.5 x 13.0 -0.50 pitch size. Ironwood Grypper socket, part number **GR1135-XXXX**, was designed for the new UFS 4.0 form factor of 153 BGA 11.0 x 13.0 – 0.50 pitch. To connect a device, simply insert the device into the socket by pressing on top of the device, no lid is required. The unique geometry of the contact grips onto the solder balls of the device. To remove the device a simple extraction tool can be used to pop the device back out of the socket and it is ready to install another device. This Grypper socket has excellent electrical performance of – 1dB insertion loss greater than 25.0 GHz. Force required to insert a device is only 25 grams / contact. The socket is sold in three configurations; sockets with a RoHS solder ball (SAC 305) replicates the device. The socket configured with SnPb solder balls allow easy reflow/attachment onto a PCB that already has components mounted. The lower melting temperature of the SnPb solder will not affect any adjacent components that might be close to the target area where the socket is to be placed. The socket can also be purchased with No solder balls. No solder ball version requires the use of a 0.2mm thick stencil for the correct amount of solder paste allowing any type of solder paste the customer's lab might use for attachment.



(July, 2022)

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